SILICON WAFER AND METHOD OF MANUFACTURING THE SAME

ABSTRACT

To provide a silicon wafer which can suppress both occurrences of slip dislocation and warpage in device manufacturing processes and a method of manufacturing the same.

A silicon wafer according to the present invention is a silicon wafer having BMDs each having an octahedron shape. BMDs located at a position shallower than the silicon wafer surface by a depth of 20 μm or more and having a diagonal length of 200 nm or more have a concentration of 2 x $10^9/cm^3$ or less, and a BMD located at a position having a depth 50 μm or more and has a diagonal length of 10 nm or more to 50 nm or less has a concentration of 1 x $10^{12}/cm^3$ or more.

[Selected Diagram] Non